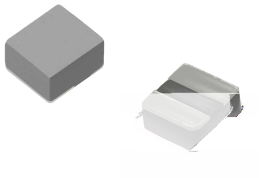
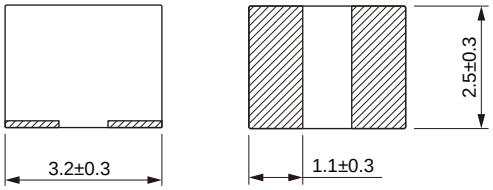
Wire Wound Molded SMD Power Inductors
Size 32251B



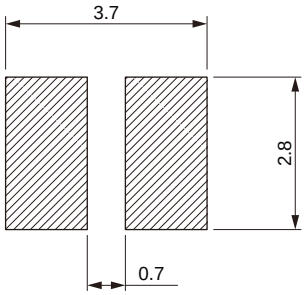
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Dimensions: [mm]



Land Pattern: [mm]

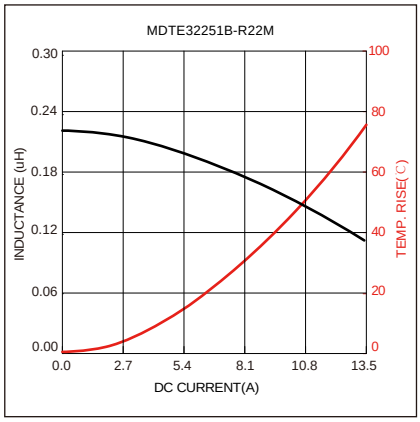


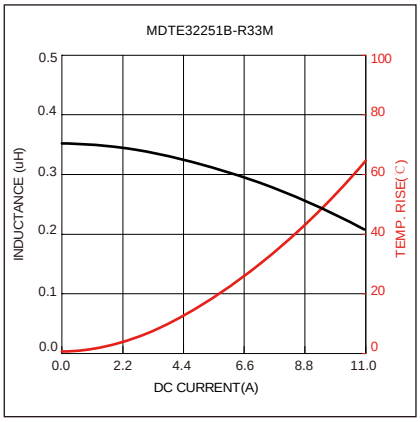
Electrical Properties:

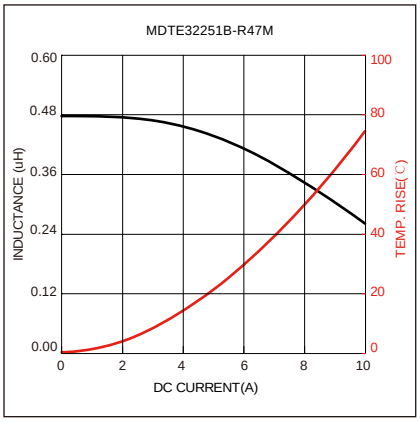
Part No	Inductance @ 1MHz/1V (μH)	Tolerance	Satura on Current Typ. (A)	Satura on Current Max. (A)	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	DC Resistance Max. (mΩ)
MDTE32251B-R22M	0.22	±20%	9.3	8.7	9.5	9.0	8.5
MDTE32251B-R33M	0.33	±20%	9.2	8.6	8.5	8.0	12
MDTE32251B-R47M	0.47	±20%	8.3	7.5	7.1	6.6	19
MDTE32251B-R68M	0.68	±20%	7.4	6.9	6.3	5.8	24
MDTE32251B-1R0M	1.00	±20%	6.6	5.8	5.7	5.2	30
MDTE32251B-2R2M	2.20	±20%	4.9	4.4	4.2	3.7	70
MDTE32251B-3R3M	3.30	±20%	3.5	3.1	3.2	2.8	95
MDTE32251B-4R7M	4.70	±20%	2.9	2.5	2.5	2.0	135

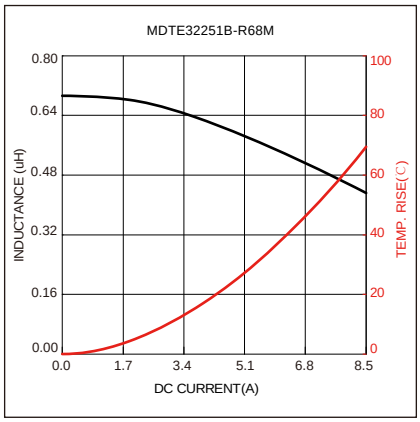
Saturation Current will cause L to drop approximately 30%
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

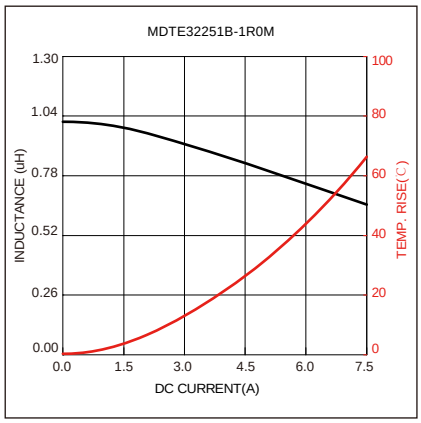
Typical Electrical Characteristics:

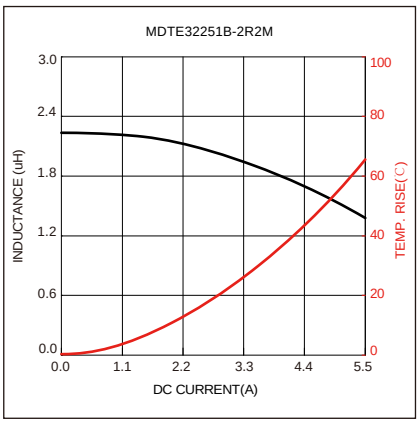


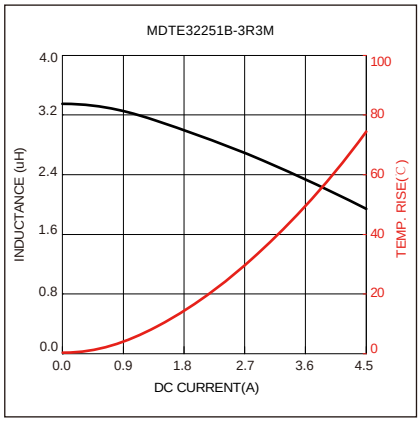


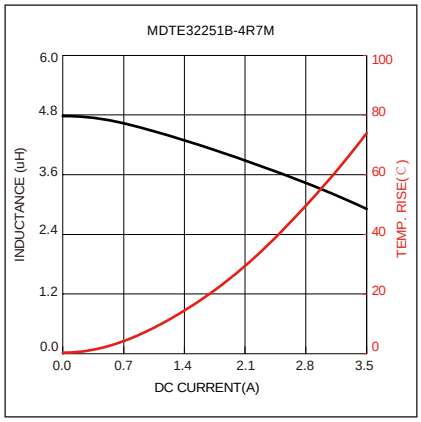












Soldering Reflow:

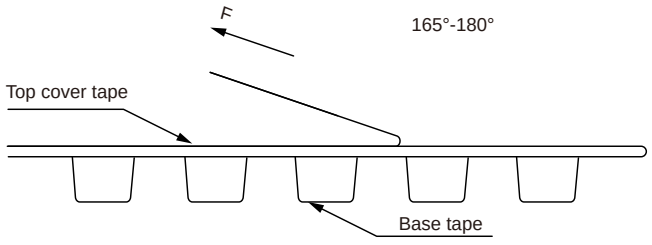
Packaging Information:

Tape Dimension:



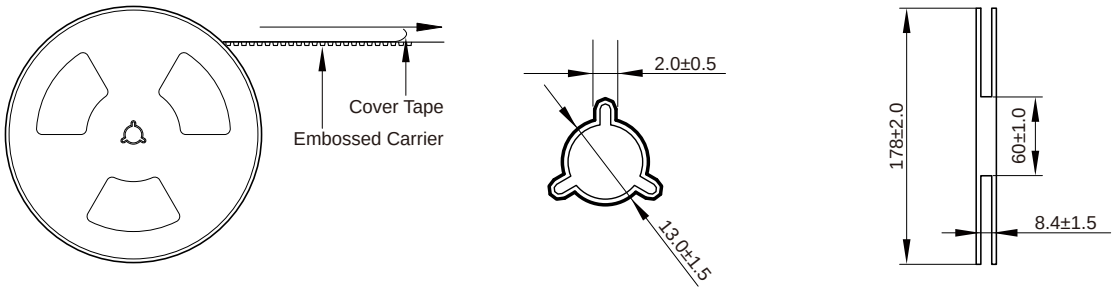
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE32251B	2.9±0.1	3.6±0.1	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.1	1.4±0.1	1.75±0.1	0.25±0.05

Peel force of top cover tape:

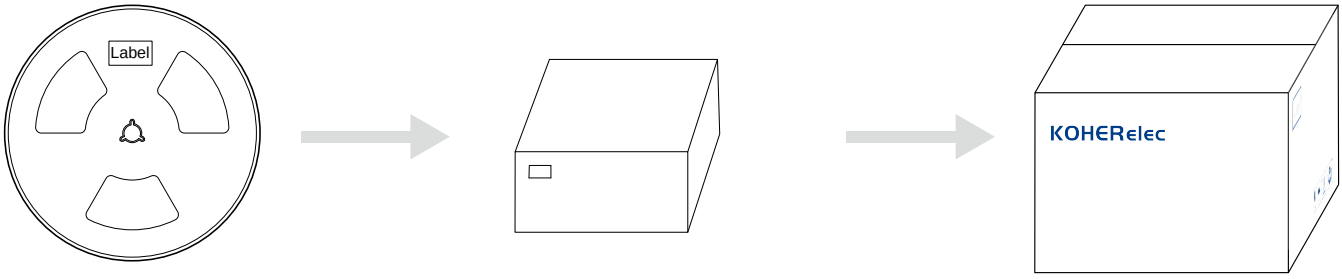


The peel force of top cover tape shall be between 0.1 to 0.98 N

Reel Dimension：[mm]



Packaging Quantity:



3000 Pcs/Reel

5 Reel /Inner box(15K Pcs)

8 Inner box/Carton box(120K Pcs)

Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.